

# semiconductor packaging news

EV Group Lithography Solutions for HI and WLP to Be Highlighted at ECTC 2022 – May 31, 2022

## semiconductor packaging news

We search for industry news, so you don't need to.

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May 31, 2022

### China Woos Foreign Investors as US Pushes for Supply Chain Decoupling

China's coastal Jiangsu province, a key chip manufacturing hub, will host a special online event to encourage foreign semiconductor design firms to partner with local peers, as the country moves to strengthen its industrial ties with the outside world amid US efforts to reduce China's role in the global chip supply chain. The online seminar, scheduled for next month, is designed to promote ...

South China Morning Post



### Ultrasonic/Thermosonic Bonding Paper

Ultrasonic power is introduced during thermocompression bonding to perform die bonding at low temperature & pressure. Paper identifies processes to improve thermosonic bonding. Read more.



TRESKY Automation

### Better Bonds, with Atmospheric Plasma

Our Atmospheric Plasma systems prepare surfaces for direct bonding, remove residue, and prepare surfaces for adhesion. Click Here to learn more.



Ontos Equipment Systems

### Samsung likely to begin groundbreaking for U.S. chip plant next month

Samsung Electronics Co. is expected to hold a groundbreaking ceremony for a US\$17 billion chip fabrication plant in Taylor, Texas, next month, industry sources said. ...

Yonhap News Agency

### Why AgCoat® Prime, why now?

Gold's properties have made it an essential material for bonding wires' performance, its price has limited economy of scales. This paper identifies a solution that maintains ...

Technical Paper

### Why Taiwan's success in semiconductors is not helping its quantum computer tech research

The year 2022 looks poised to become a breakthrough year for quantum computer hardware. But Taiwan, where half of the world's chips are manufactured, is ironically lagging ...

Digitimes

### Technical Papers

- [Dispositioning Hermetic Microelectronic Components With High Internal Moisture](#)
- [Automated Wafer TTV & Shape Metrology](#)
- [Empowering RF Front End Cellular Innovations with DSMBGA](#)
- [Diamond's thermal management properties are enabling higher performance solutions](#)
- [How to Cold Bump Pull?](#)
- [The Essential Guide for High-Reliability BGA Component Re-balling](#)
- [Advancing silicon photonics physical verification through innovation](#)

### Automated Epoxy Die Attach

With rapid time-to-market requirements, automating the packaging process has become more critical than ever. Epoxy die attach is a consistent, reliable & flexible form of component attach. Palomar Technologies, Inc.



Today's Sponsor



### Test Your Knowledge

What is the more common name for dihydrogen monoxide?

See answer below.

### Thermal Interface

#### Adhesives/Greases/Gels/Pads

Patented compressible phase-change pads to provide void-free interfaces, stress-free thermal adhesives and proven highest performing greases and gels.



AI Technology, Inc.

### Press Releases

#### EV Group Lithography Solutions for HI and WLP to Be Highlighted at ECTC 2022

EV Group (EVG) announced that new developments in heterogeneous integration ...

EV Group

#### ZEISS expands presence in Hungary

With the acquisition of ETEO Software Factory Kft., a software development company based ...

ZEISS

#### Technology Industry Veteran Joe Stockunas Joins SEMI as Americas President

SEMI announced that technology industry veteran and longtime SEMI member Joe Stockunas ...

SEMI

#### STMicroelectronics' high-bandwidth common-mode filters ensure signal integrity

New common-mode filters from STMicroelectronics have an extremely wide ...

STMicroelectronics

#### NanoResolution MRS™ Sensor

Increase throughput with the NanoResolution MRS™ Sensor that is 2-3X faster, delivering greater than 25 wafers (300mm) per hour.

Learn more.  
**CyberOptics Corporation**



#### Amkor Antenna in Package (AiP) Solutions

As demand for packages that support 5G increase, Amkor is ready with the successful implementation of AiP/AoP technology. Learn more.  
**Amkor Technology, Inc.**



#### SEMI Europe Urges Swift Adoption of European Chips Act

SEMI Europe urged swift adoption of the European Chips Act and invited discussions on the legislation with the European Parliament, Member States and the European ...  
**SEMI**

#### Samsung's Lee meets Intel CEO in Seoul to discuss chip cooperation

Samsung Electronics Co. Vice Chairman Lee Jae-yong met with Patrick P. Gelsinger, chief executive of Intel Corp., in Seoul and discussed cooperation in the chip sector, ...  
**Yonhap News Agency**

#### Week In Review: Manufacturing, Test

Broadcom announced it will acquire cloud computing and virtualization company VMware for about \$61 billion in cash and stock, and assume \$8 billion in VMware net debt. ...  
**Semiconductor Engineering**

**Cost-Effective Exhaust Abatement for effluent gases**  
**HCl, HF, PFCs, TVOCs, NOx.**  
Guaranteed NESHAP compliance  
20+ years serving water fab, semicon, microelectronics  
**Tri-Mer CORPORATION**  
Made in USA

**SOSS MicroTec**  
**Hybrid Bonding**

**3D-MICROMAC**  
**microPREP™ PRO**  
Sample Preparation  
» High ablation rates  
» Larger sample size  
» Micron-level precision  
[www.3d-micromac.com](http://www.3d-micromac.com)

#### Korean chipmakers urge government support to foster and keep talent

A talent shortage is challenging South Korea's chipmaking industry. Chipmakers including Samsung Electronics and SK Hynix have urged the country's new government ...  
**Digitimes**

#### NXP to strengthen R&D to support India's chip-making plans

Many global semiconductor companies have welcomed the Indian government's latest initiative to promote local semiconductor manufacturing. With its range of ...  
**Digitimes**

#### From somebody to nobody: TSMC faces uphill battle in U.S. talent war

On a quiet April morning, cranes, bulldozers, trucks and construction workers bustled down streets in two places lying in opposite directions from Phoenix: those to its ...  
**Nikkei Asia**

#### Two Part Epoxy Features Ultra Low CTE

Master Bond EP30LTE-2 epoxy has an extraordinarily low CTE of 10-13 x 10<sup>-6</sup> in/in/°C along with high dimensional stability and electrical insulation.

**Master Bond**



#### Transform Your Sample Prep with LaserFIB

Rapidly access deeply buried features with precise targeting. Get site-specific cross-section results in minutes to hours. How? Watch our webinar.  
**ZEISS Microscopy**



#### Supercharging Hyperscale and HPC with Superchips

Nvidia launched the concept of superchips at its GTC conference in March. "Superchip" is what the company calls its modules with two computing die on it; the Grace ...  
**EE Times**

#### Thermal camera marketplace: Chinese players take the stage

A lot of work has gone into commercializing and selling thermal cameras from Chinese ...  
**Yole Développement**

#### Salvage Your Components Quickly!

Do you have BGA, QFP, or LGA components that will meet your needs but currently soldered to obsolete PCB's? We can salvage components from PCB's & prep for machine assembly. Learn more.  
**Circuit Technology Center**



#### Quote of the Day

"Do not confuse motion and progress. A rocking horse keeps moving but does not make any progress."

**Alfred A. Montapert**

#### 2x Faster, ½ the Capital Cost, ½ the Footprint

Looking for revolutionary productivity for your advanced technologies? YES Plasma Resist/Descum Systems have high throughput & strip rate.  
**Yield Engineering Systems, Inc.**



#### All-in-one printing of the Future

Welco® AP5112 Type 7 paste enables the single-step printing process for both flip-chip & passive component attach, which significantly reduces assembly cost and solder defects.  
**Heraeus Advanced Packaging**



#### What Year Was It?

##### Big Ben Rings for the First Time

The famous tower clock known as Big Ben, located at the top of the 320-foot-high St. Stephen's Tower, rings for the first time.



**The day was May 31. What year was it?**

#### Alternatives to Isopropyl Alcohol (IPA)

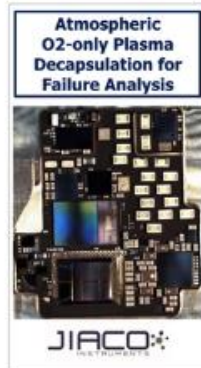
Having a hard time finding IPA? KYZEN offers safe, affordable alternatives globally! To learn more, fill out this form to download our technical brief!  
**KYZEN**



#### Best Value Plasma Systems

The PE-100 utilizes a capacitive parallel plate design for the most effective plasma generation available. Our systems offer uniform plasma with a low environmental impact at a great value.  
**Plasma Etch**





**Cartoon of the Day**



"I do not ignore your e-mails. I personally delete each and every one!"

Copyright © Randy Glasbergen

**Calendar**

- [Jun 1, 2022: Overview of Semiconductor Manufacturing for Asian Attendees](#)
- [Jun 1, 2022: Overview of Semiconductor Manufacturing Webinar for Asian Attendees](#)
- [Jun 9, 2022: Overview of semiconductor manufacturing webinar for America attendees](#)
- [Jun 15, 2022: SEMICON China 2022](#)

**Two Part Epoxy Features Ultra Low CTE**

Master Bond EP30LTE-2 epoxy has an extraordinarily low CTE of 10-13 x 10<sup>-6</sup> in/in/°C along with high dimensional stability and electrical insulation.

**Master Bond**



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Rapidly access deeply buried features with precise targeting. Get site-specific cross-section results in minutes to hours. How? Watch our webinar.

**ZEISS Microscopy**



**FLEX Conf. & Exhibition 2022 July 11-14**

FLEX is the annual touchpoint centered around flexible hybrid, printed electronics — FHE products and services. Register now to save.



**SEMI**

**Test Your Knowledge Answer**

What is the more common name for dihydrogen monoxide?

Answer: Water

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